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Attorney's Docket No. S1022/8246
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7. (Amended) The electronic circuit of claim 1, wherein the surface of the base which does not receive the double faced adhesive is provided to receive the printing of a pattern, of a text or of a code.

8. (Amended) A method of manufacturing the circuit of claim 1, wherein the attachment of the double faced adhesive on the base includes the steps of:

forming a rectangle of double faced adhesive including a slot,

gluing the adhesive rectangle on a packaging protective film,

ungluing the adhesive rectangle from the protective film, and assembling it on the base.

REMARKS

This is a preliminary amendment in which the claims have been amended to place them in better form before initial examination by the Examiner. Favorable action is hereby earnestly solicited.

Respectfully submitted,

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AMENDED CLAIMS SHOWING THE AMENDMENTS

1. (Amended) An electronic circuit including a planar base [(14)], an antenna [(16)] attached on a first surface of the base, and a chip [(12)] connected to the antenna, characterized in that a double faced adhesive [(20)] is glued on one of the base surfaces, a slot [(21)] being made in the double faced adhesive and the chip being arranged at least partially in this slot.

2. (Amended) The electronic circuit of claim 1, [characterized in that] wherein the chip is glued on the first surface of the base and is connected to the antenna by connection wires [(18)], the wires and the chip being covered with a drop of resin [(19, 22)].

3. (Amended) The electronic circuit of claim 1, [characterized in that] wherein the etched surface of the chip faces the first surface of the base, and the chip is connected to the antenna by welding beads [(26)].

4. (Amended) The electronic circuit of claim 1, [characterized in that] wherein the etched surface of the chip faces the back of the first surface of the base, the chip is placed in a slot [(21)] made through the base, and the chip is connected to the antenna by welding beads [(26)], the chip being attached to the base by a drop of resin [(22)].

5. (Amended) The electronic circuit of claim 1, [characterized in that] wherein the etched surface of the chip faces the back of the first surface of the base and the chip is connected to the antenna by welding beads [(26)] located in connection slots [(25)] going through the base [(14)], the chip being attached to the base by a drop of resin [(22)].

6. (Amended) The electronic circuit of [any of the preceding claims, characterized in that] claim 1, wherein the base [(14)] is made of a flexible sheet.

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7. (Amended) The electronic circuit of [any of the preceding claims, characterized in that] claim 1, wherein the surface of the base which does not receive the double faced adhesive is provided to receive the printing of a pattern, of a text or of a code [(38)].

8. (Amended) A method of manufacturing the circuit of claim 1, [characterized in that] wherein the attachment of the double faced adhesive on the base includes the steps of:

forming a rectangle of double faced adhesive [(20)] including a slot [(21)],

gluing the adhesive rectangle on a packaging protective film [(24)],

ungluing the adhesive rectangle from the protective film, and assembling it on the base [(14)].